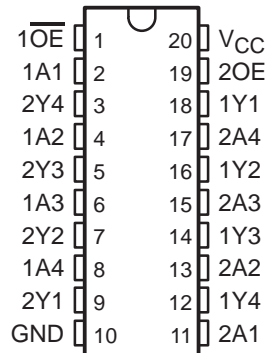


# SN54HC241, SN74HC241 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

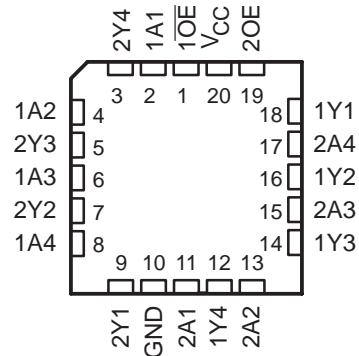
SCLS300C – JANUARY 1996 – REVISED AUGUST 2003

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Outputs Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 11$  ns
- $\pm 6$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers

SN54HC241 . . . J OR W PACKAGE  
SN74HC241 . . . DW, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54HC241 . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The 'HC241 devices are organized as two 4-bit buffers/drivers with separate output-enable ( $1\overline{OE}$  and  $2OE$ ) inputs. When  $1\overline{OE}$  is low or  $2OE$  is high, the device passes noninverted data from the A inputs to the Y outputs. When  $1\overline{OE}$  is high or  $2OE$  is low, the outputs for the respective buffers/drivers are in the high-impedance state.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 85°C	PDIP – N	Tube of 20	SN74HC241N	SN74HC241N	
	SOIC – DW	Tube of 25	SN74HC241DW	HC241	
		Reel of 2000	SN74HC241DWR		
	SOP – NS	Reel of 2000	SN74HC241NSR	HC241	
	TSSOP – PW		Reel of 70	SN74HC241PW	HC241
			Reel of 2000	SN74HC241PWR	
Reel of 250			SN74HC241PWT		
-55°C to 125°C	CDIP – J	Tube of 20	SNJ54HC241J	SNJ54HC241J	
	CFP – W	Tube of 85	SNJ54HC241W	SNJ54HC241W	
	LCCC – FK	Tube of 55	SNJ54HC241FK	SNJ54HC241FK	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54HC241, SN74HC241 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

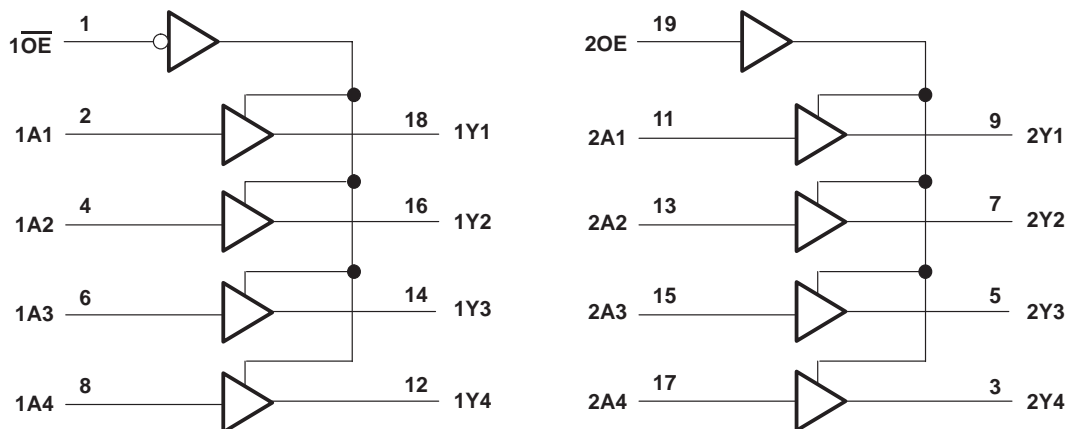
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## FUNCTION TABLES

INPUTS		OUTPUT
1OE	1A	1Y
L	H	H
L	L	L
H	X	Z

INPUTS		OUTPUT
2OE	2A	2Y
H	H	H
H	L	L
L	X	Z

### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	$\pm 35$ mA
Continuous current through $V_{CC}$ or GND	$\pm 70$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54HC241, SN74HC241 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 3)

		SN54HC241			SN74HC241			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	2	5	6	2	5	6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V		1.5	1.5		V	
		V <sub>CC</sub> = 4.5 V		3.15	3.15			
		V <sub>CC</sub> = 6 V		4.2	4.2			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V			0.5		0.5	V
		V <sub>CC</sub> = 4.5 V			1.35		1.35	
		V <sub>CC</sub> = 6 V			1.8		1.8	
V <sub>I</sub>	Input voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
Δt/Δv	Input transition rise/fall time	V <sub>CC</sub> = 2 V			1000		1000	ns
		V <sub>CC</sub> = 4.5 V			500		500	
		V <sub>CC</sub> = 6 V			400		400	
T <sub>A</sub>	Operating free-air temperature		-55	125		-40	85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC241		SN74HC241		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998		1.9		1.9	V	
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I <sub>OH</sub> = -6 mA	4.5 V	3.98	4.3		3.7		3.84		
		I <sub>OH</sub> = -7.8 mA	6 V	5.48	5.8		5.2		5.34		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		I <sub>OL</sub> = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0		6 V		±0.1	±100		±1000		±1000	nA
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or 0		6 V		±0.01	±0.5		±10		±5	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0		6 V			8		160		80	μA
C <sub>i</sub>			2 V to 6 V		3	10		10		10	pF



# SN54HC241, SN74HC241 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$   
(unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC241		SN74HC241		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	2 V		39	115		170		145	ns
			4.5 V		12	23		34		29	
			6 V		11	20		29		25	
$t_{en}$	$\overline{OE}$ or OE	Y	2 V		60	150		225		190	ns
			4.5 V		17	30		45		38	
			6 V		15	26		38		32	
$t_{dis}$	$\overline{OE}$ or OE	Y	2 V		40	150		225		190	ns
			4.5 V		18	30		45		38	
			6 V		17	26		38		32	
$t_t$		Y	2 V		28	60		90		75	ns
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	

switching characteristics over recommended operating free-air temperature range,  $C_L = 150 \text{ pF}$   
(unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC241		SN74HC241		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	2 V		50	165		245		210	ns
			4.5 V		16	33		49		42	
			6 V		14	28		42		35	
$t_{en}$	$\overline{OE}$ or OE	Y	2 V		100	200		300		250	ns
			4.5 V		20	40		60		50	
			6 V		17	34		51		43	
$t_t$		Y	2 V		45	210		315		265	ns
			4.5 V		17	42		63		53	
			6 V		13	36		53		45	

operating characteristics,  $T_A = 25^\circ\text{C}$

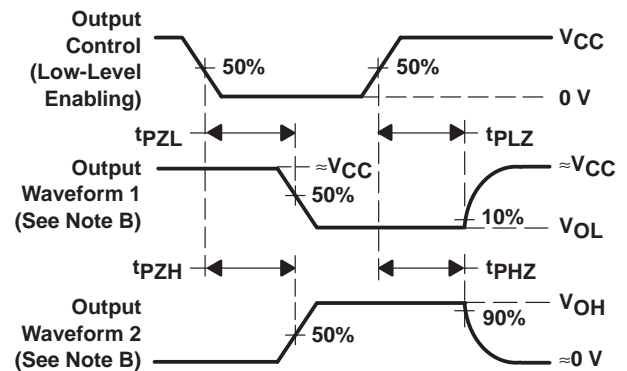
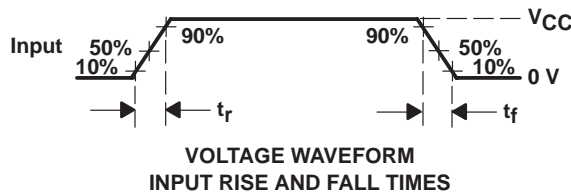
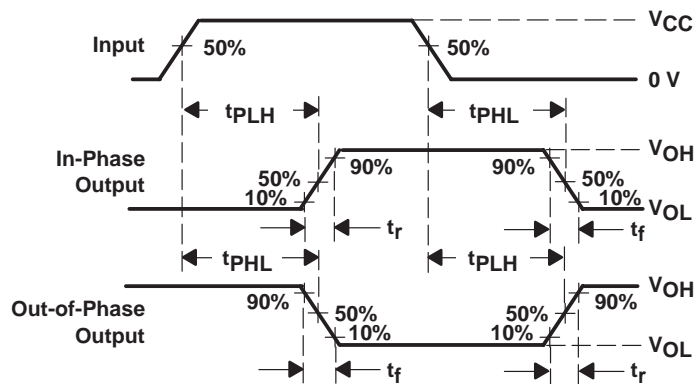
PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance per buffer/driver	No load	35	pF



PARAMETER MEASUREMENT INFORMATION



PARAMETER	$R_L$	$C_L$	S1	S2
$t_{en}$	$t_{PZH}$	1 k $\Omega$ 50 pF or 150 pF	Open	Closed
	$t_{PZL}$		Closed	Open
$t_{dis}$	$t_{PHZ}$	1 k $\Omega$ 50 pF	Open	Closed
	$t_{PLZ}$		Closed	Open
$t_{pd}$ or $t_t$	--	50 pF or 150 pF	Open	Open



- NOTES:
- A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.
  - D. The outputs are measured one at a time with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/65704BRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65704BRA	<a href="#">Samples</a>
M38510/65704BRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 65704BRA	<a href="#">Samples</a>
SN54HC241J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC241J	<a href="#">Samples</a>
SN74HC241DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC241	<a href="#">Samples</a>
SN74HC241DWE4	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC241	<a href="#">Samples</a>
SN74HC241DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC241	<a href="#">Samples</a>
SN74HC241DWRG4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC241	<a href="#">Samples</a>
SN74HC241N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC241N	<a href="#">Samples</a>
SN74HC241NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC241	<a href="#">Samples</a>
SN74HC241PW	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC241	<a href="#">Samples</a>
SN74HC241PWG4	ACTIVE	TSSOP	PW	20	70	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC241	<a href="#">Samples</a>
SN74HC241PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC241	<a href="#">Samples</a>
SN74HC241PWRE4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC241	<a href="#">Samples</a>
SNJ54HC241FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54HC 241FK	<a href="#">Samples</a>
SNJ54HC241J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54HC241J	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54HC241, SN74HC241 :**

● Catalog : [SN74HC241](#)

● Military : [SN54HC241](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC241DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74HC241NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74HC241PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC241DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74HC241NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74HC241PWR	TSSOP	PW	20	2000	853.0	449.0	35.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

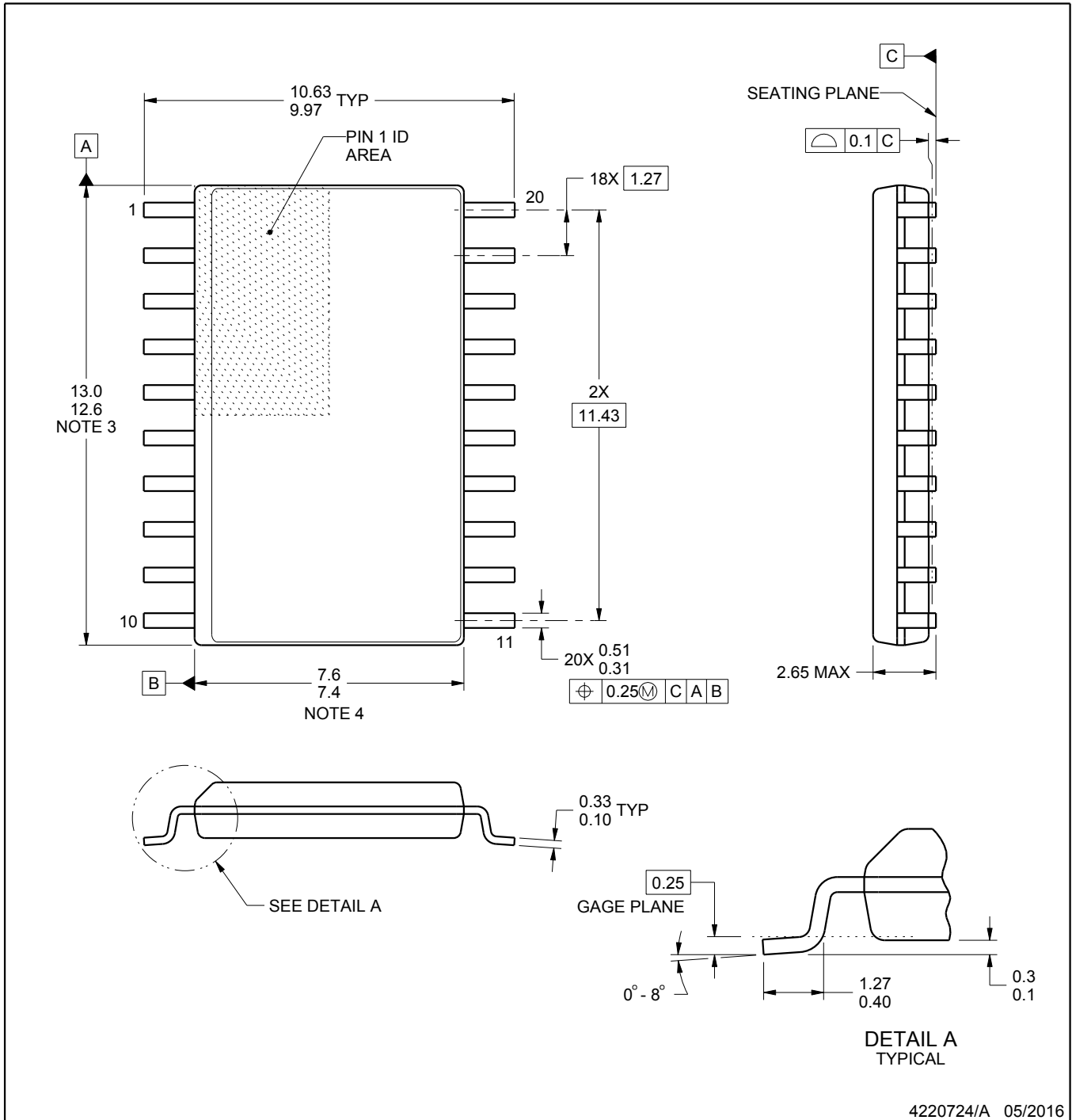
# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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